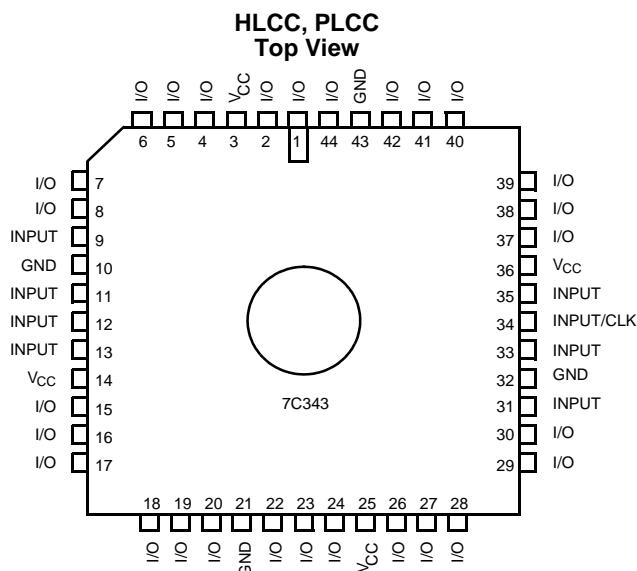


## Pin Configuration



## Selection Guide

	<b>7C343B-25</b>	<b>7C343B-30</b>	<b>7C343B-35</b>
Maximum Access Time (ns)	25	30	35

## Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... -65°C to +135°C

Ambient Temperature with  
Power Applied ..... -65°C to +135°C

Maximum Junction Temperature  
(Under Bias) ..... 150°C

Supply Voltage to Ground Potential<sup>[1]</sup> ..... -2.0V to +7.0V

DC Output Current, per Pin<sup>[1]</sup> ..... -25 mA to +25 mA

DC Input Voltage<sup>[1]</sup> ..... -2.0V to +7.0V

## Operating Range<sup>[2]</sup>

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0°C to +70°C	5V ±5%
Industrial	-40°C to +85°C	5V ±10%
Military	-55°C to +125°C (Case)	5V ±10%

### Note:

1. Minimum DC input is -0.3V. During transactions, the inputs may undershoot to -2.0V or overshoot to 7.0V for input currents less than 100 mA and periods shorter than 20 ns.
2. The Voltage on any input or I/O pin cannot exceed the power pin during power-up.

### Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
$V_{CC}$	Supply Voltage	Maximum $V_{CC}$ rise time is 10 ms	4.75(4.5)	5.25(5.5)	V
$V_{OH}$	Output HIGH Voltage	$I_{OH} = -4.0$ mA DC <sup>[3]</sup>	2.4		V
$V_{OL}$	Output LOW Voltage	$I_{OL} = 8$ mA DC <sup>[3]</sup>		0.45	V
$V_{IH}$	Input HIGH Level		2.0	$V_{CC}+0.3$	V
$V_{IL}$	Input LOW Level		-0.3	0.8	V
$I_{IX}$	Input Current	$V_I = V_{CC}$ or ground	-10	+10	μA
$I_{OZ}$	Output Leakage Current	$V_O = V_{CC}$ or ground	-40	+40	μA
$t_R$	Recommended Input Rise Time			100	ns
$t_F$	Recommended Input Fall Time			100	ns

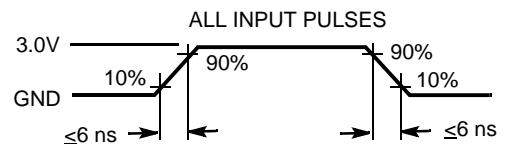
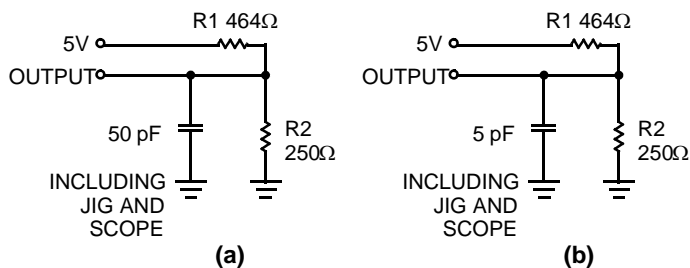
### Capacitance

Parameter	Description	Test Conditions	Max.	Unit
$C_{IN}$	Input Capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz	10	pF
$C_{OUT}$	Output Capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz	20	pF

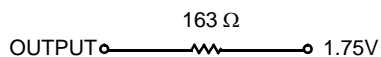
**Note:**

3. The  $I_{OH}$  parameter refers to high-level TTL output current; the  $I_{OL}$  parameter refers to low-level TTL output current.

### AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT (commercial/military)



## Programmable Interconnect Array

The Programmable Interconnect Array (PIA) solves interconnect limitations by routing only the signals needed by each logic array block. The inputs to the PIA are the outputs of every macrocell within the device and the I/O pin feedback of every pin on the device.

Unlike masked or programmable gate arrays, which induce variable delay dependent on routing, the PIA has a fixed delay. This eliminates undesired skews among logic signals, which may cause glitches in internal or external logic. The fixed delay, regardless of programmable interconnect array configuration, simplifies design by ensuring that internal signal skews or races are avoided. The result is simpler design implementation, often in a single pass, without the multiple internal logic placement and routing iterations required for a programmable gate array to achieve design timing objectives.

## Design Recommendations

Operation of the devices described herein with conditions above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this data sheet is not implied. Exposure to absolute maximum ratings conditions for extended periods of time may affect device reliability. The CY7C343B contains circuitry to protect device pins from high static voltages or electric fields; however, normal precautions should be taken to avoid applying any voltage higher than maximum rated voltages.

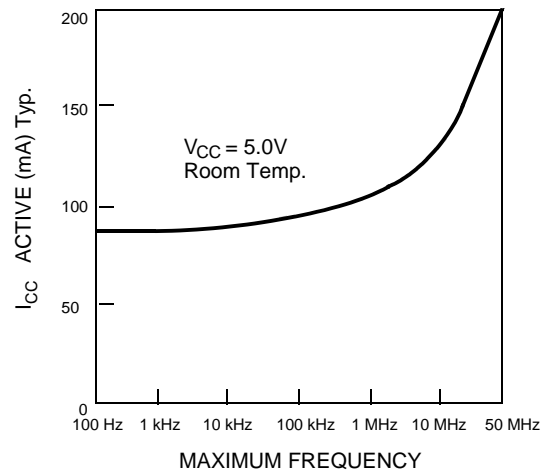
For proper operation, input and output pins must be constrained to the range  $GND \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{CC}$ . Unused inputs must always be tied to an appropriate logic level (either  $V_{CC}$  or GND). Each set of  $V_{CC}$  and GND pins must be connected together directly at the device. Power supply decoupling capacitors of at least 0.2  $\mu F$  must be connected between  $V_{CC}$  and GND. For the most effective decoupling, each  $V_{CC}$  pin should be separately decoupled to GND, directly at the device. Decoupling capacitors should have good frequency response, such as monolithic ceramic types.

## Timing Considerations

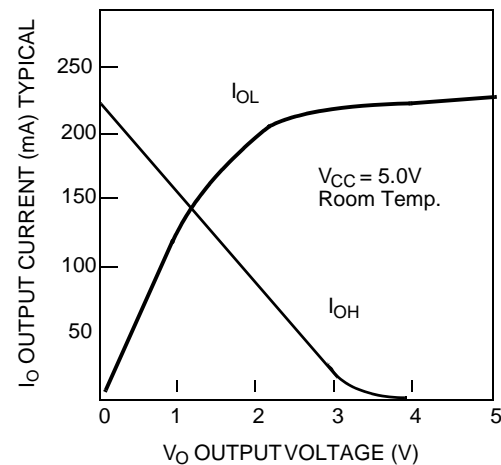
Unless otherwise stated, propagation delays do not include expanders. When using expanders, add the maximum expander delay  $t_{EXP}$  to the overall delay. Similarly, there is an additional  $t_{PIA}$  delay for an input from an I/O pin when compared to a signal from a straight input pin.

When calculating synchronous frequencies, use  $t_{S1}$  if all inputs are on the input pins. When expander logic is used in the data path, add the appropriate maximum expander delay,  $t_{EXP}$  to  $t_{S1}$ . Determine which of  $1/(t_{WH} + t_{WL})$ ,  $1/t_{CO1}$ , or  $1/(t_{EXP} + t_{S1})$  is the lowest frequency. The lowest of these frequencies is the maximum data path frequency for the synchronous configuration.

## Typical $I_{CC}$ vs. $f_{MAX}$



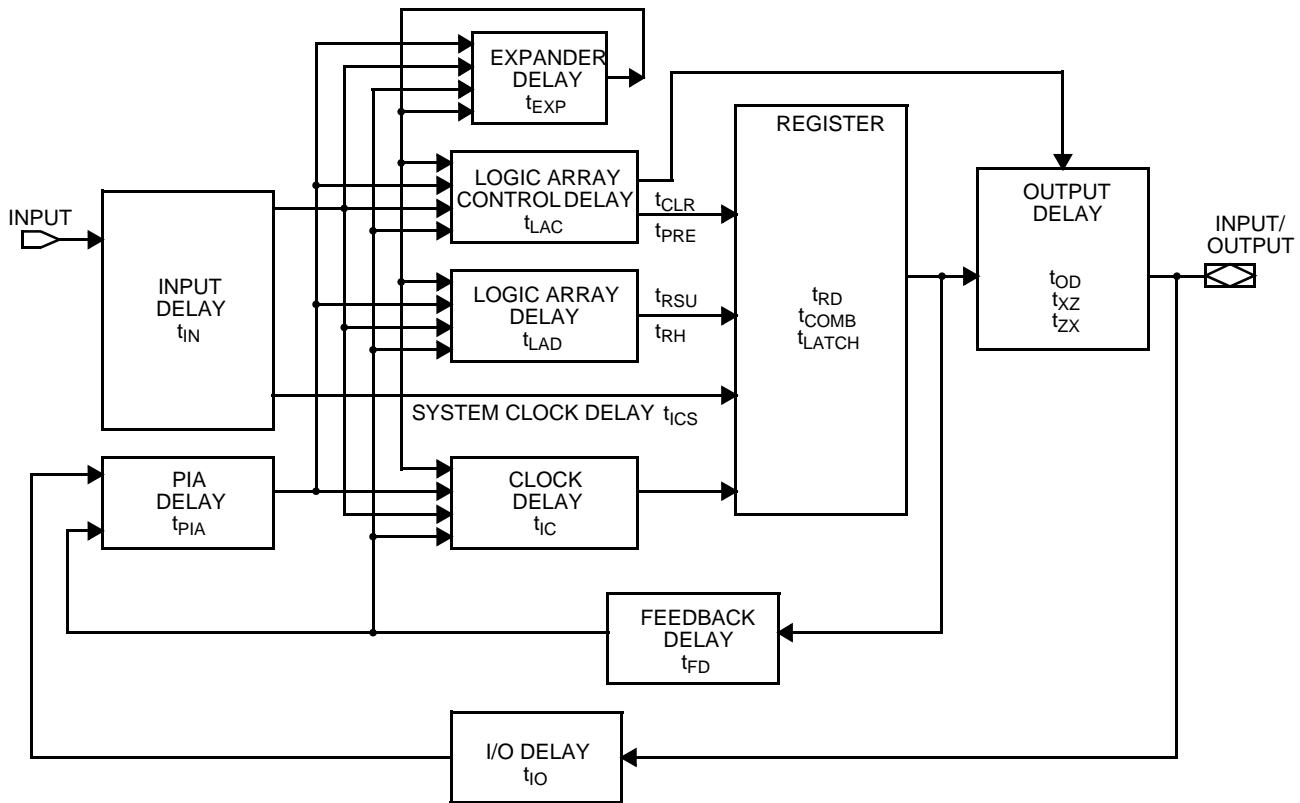
## Output Drive Current



When calculating external asynchronous frequencies, use  $t_{AS1}$  if all inputs are on dedicated input pins.

When expander logic is used in the data path, add the appropriate maximum expander delay,  $t_{EXP}$  to  $t_{AS1}$ . Determine which of  $1/(t_{AWH} + t_{AWL})$ ,  $1/t_{ACO1}$ , or  $1/(t_{EXP} + t_{AS1})$  is the lowest frequency. The lowest of these frequencies is the maximum data path frequency for the asynchronous configuration.

The parameter  $t_{OH}$  indicates the system compatibility of this device when driving other synchronous logic with positive input hold times, which is controlled by the same synchronous clock. If  $t_{OH}$  is greater than the minimum required input hold time of the subsequent synchronous logic, then the devices are guaranteed to function properly with a common synchronous clock under worst-case environmental and supply voltage conditions.



**Figure 1. CY7C343B Internal Timing Model**

**External Synchronous Switching Characteristics** Over Operating Range

Parameter	Description		7C343B-25		7C343B-30		7C343B-35		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
$t_{PD1}$	Dedicated Input to Combinatorial Output Delay <sup>[4]</sup>	Com'I/Ind		25		30		35	ns
$t_{PD2}$	I/O Input to Combinatorial Output Delay <sup>[4]</sup>	Com'I/Ind		40		45		55	ns
$t_{SU}$	Global clock setup time	Com'I/ Ind	15		20		25		ns
$t_{CO1}$	Synchronous Clock Input to Output Delay <sup>[3]</sup>	Com'I/Ind		14		16		20	ns
$t_H$	Input Hold Time from Synchronous Clock Input	Com'I/Ind	0		0		0		ns
$t_{WH}$	Synchronous Clock Input HIGH Time	Com'I/Ind	8		10		12.5		ns
$t_{WL}$	Synchronous Clock Input LOW Time	Com'I/Ind	8		10		12.5		ns
$f_{MAX}$	Maximum Register Toggle Frequency <sup>[5]</sup>	Com'I/Ind	62.5		50		40		MHz
$t_{CNT}$	Minimum Global Clock Period	Com'I/Ind		20		25		30	ns
$t_{ODH}$	Output Data Hold Time After Clock	Com'I/Ind	2		2		2		ns
$f_{CNT}$	Maximum Internal Global Clock Frequency <sup>[6]</sup>	Com'I/Ind	50		40		33.3		MHz

**Notes:**

4. C1 = 35 pF.
5. The  $f_{MAX}$  values represent the highest frequency for pipeline data.
6. This parameter is measured with a 16-bit counter programmed into each LAB.



External Asynchronous Switching Characteristics Over Operating Range

Parameter	Description		7C343B-25		7C343B-30		7C343B-35		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>ACO1</sub>	Asynchronous Clock Input to Output Delay <sup>[4]</sup>	Com'l/Ind		25		30		35	ns
t <sub>AS1</sub>	Dedicated Input or Feedback Set-Up Time to Asynchronous Clock Input	Com'l/Ind	5		6		8		ns
t <sub>AH</sub>	Input Hold Time from Asynchronous Clock Input	Com'l/Ind	6		8		10		ns
t <sub>AWH</sub>	Asynchronous Clock Input HIGH Time <sup>[7]</sup>	Com'l/Ind	11		14		16		ns
t <sub>AWL</sub>	Asynchronous Clock Input LOW Time <sup>[7]</sup>	Com'l/Ind	9		11		14		ns
t <sub>ACNT</sub>	Minimum Internal Array Clock Frequency	Com'l/Ind		20		25		30	ns
f <sub>ACNT</sub>	Maximum Internal Array Clock Frequency <sup>[6]</sup>	Com'l/Ind	50		40		33.3		MHz

Internal Switching Characteristics Over Operating Range

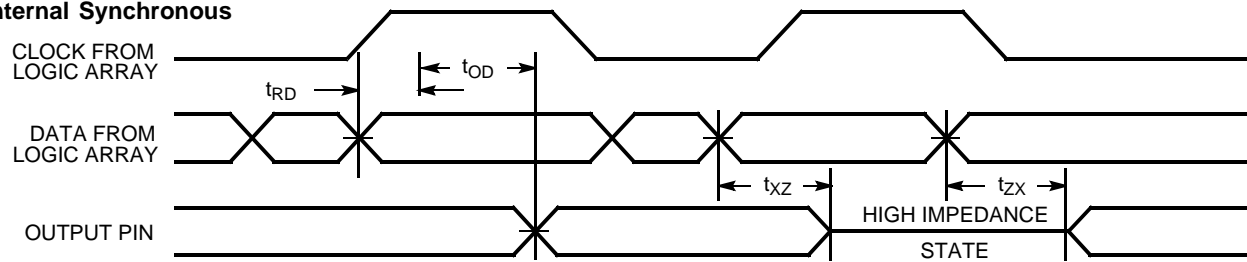
Parameter	Description		7C343B-25		7C343B-30		7C343B-35		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>IN</sub>	Dedicated Input Pad and Buffer Delay	Com'l/Ind		5		7		11	ns
t <sub>IO</sub>	I/O Input Pad and Buffer Delay	Com'l/Ind		6		6		11	ns
t <sub>EXP</sub>	Expander Array Delay	Com'l/Ind		12		14		20	ns
t <sub>LAD</sub>	Logic Array Data Delay	Com'l/Ind		12		14		14	ns
t <sub>LAC</sub>	Logic Array Control Delay	Com'l/Ind		10		12		13	ns
t <sub>OD</sub>	Output Buffer and Pad Delay <sup>[4]</sup>	Com'l/Ind		5		5		6	ns
t <sub>ZX</sub>	Output Buffer Enable Delay <sup>[4]</sup>	Com'l/Ind		10		11		13	ns
t <sub>XZ</sub>	Output Buffer Disable Delay <sup>[8]</sup>	Com'l/Ind		10		11		13	ns
t <sub>RSU</sub>	Register Set-Up Time Relative to Clock Signal at Register	Com'l/Ind	6		8		12		ns
t <sub>RH</sub>	Register Hold Time Relative to Clock Signal at Register	Com'l/Ind	4		6		8		ns
t <sub>LATCH</sub>	Flow-Through Latch Delay	Com'l/Ind		3		4		4	ns
t <sub>RD</sub>	Register Delay	Com'l/Ind		1		2		2	ns
t <sub>COMB</sub>	Transparent Mode Delay	Com'l/Ind		3		4		4	ns
t <sub>IC</sub>	Asynchronous Clock Logic Delay	Com'l/Ind		14		16		18	ns
t <sub>ICS</sub>	Synchronous Clock Delay	Com'l/Ind		3		2		1	ns
t <sub>FD</sub>	Feedback Delay	Com'l/Ind		1		1		2	ns
t <sub>PRE</sub>	Asynchronous Register Preset Time	Com'l/Ind		5		6		7	ns
t <sub>CLR</sub>	Asynchronous Register Clear Time	Com'l/Ind		5		6		7	ns
t <sub>PIA</sub>	Programmable Interconnect Array Delay Time	Com'l/Ind		14		16		20	ns

Notes:

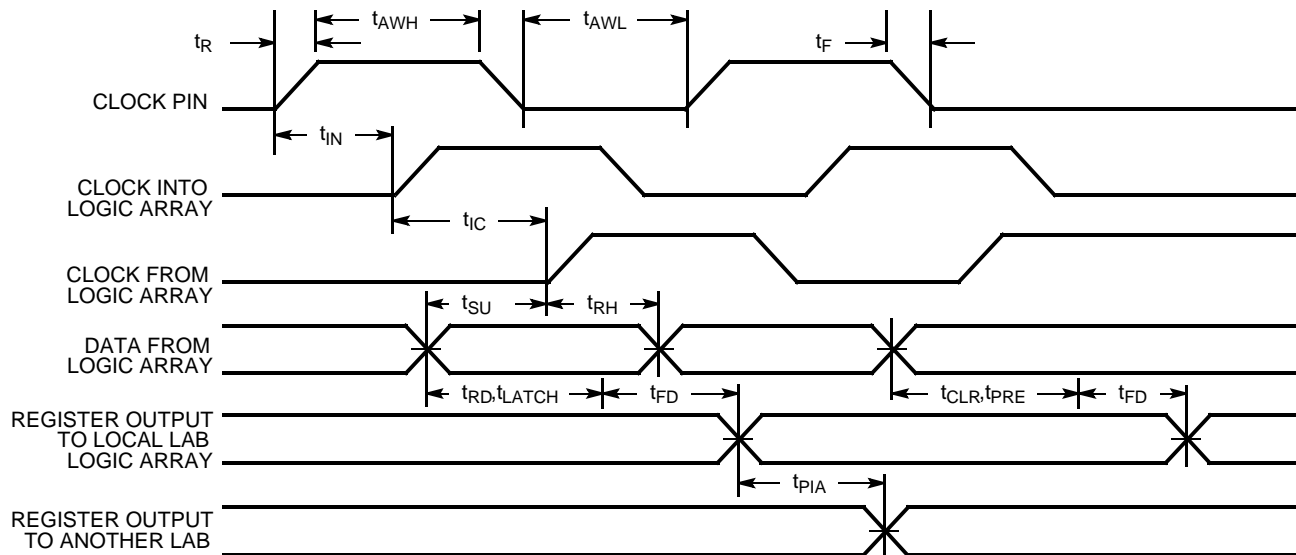
7. This parameter is measured with a positive-edge-triggered clock at the register. For negative-edge clocking, the t<sub>ACH</sub> and t<sub>ACL</sub> parameter must be swapped.  
8. C1 = 5 pF.

## Switching Waveforms

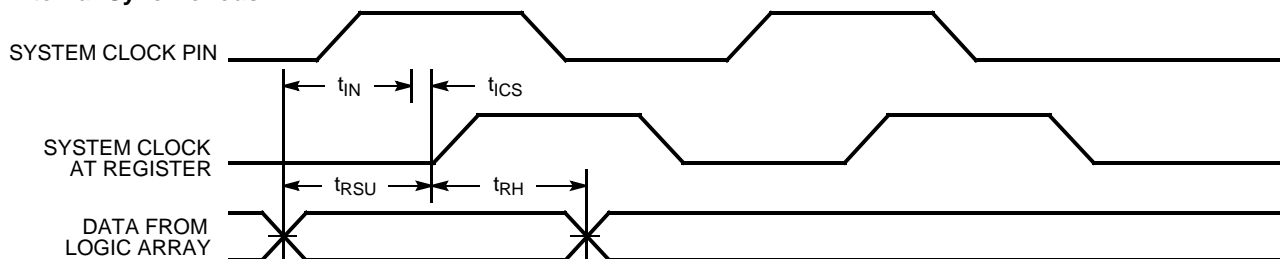
### Internal Synchronous



### Internal Asynchronous

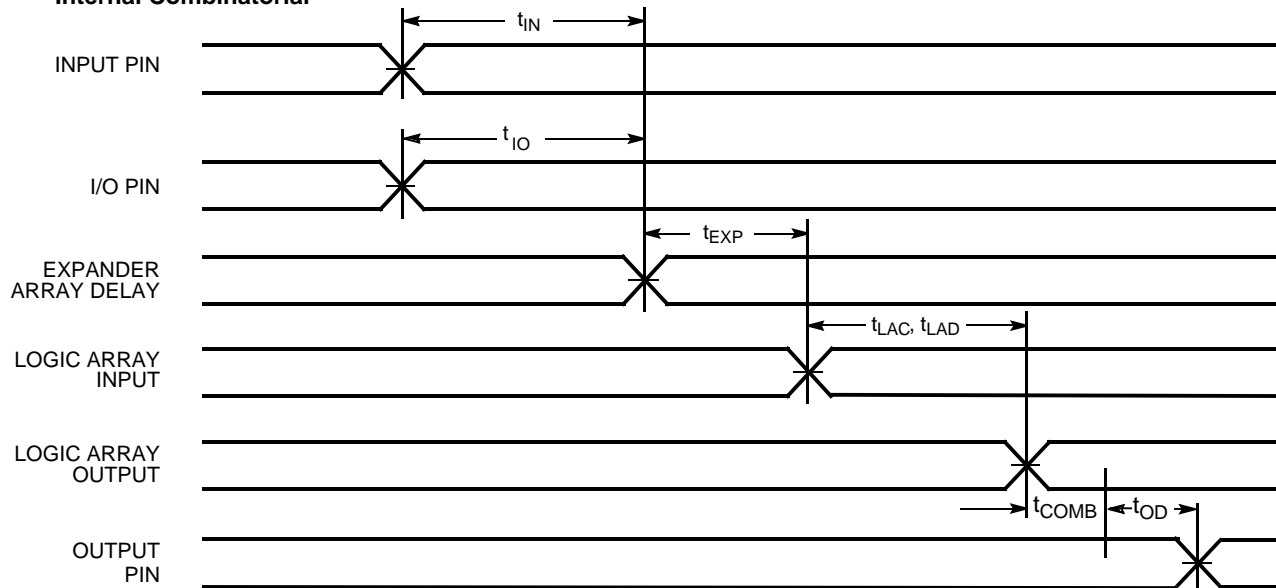


### Internal Synchronous

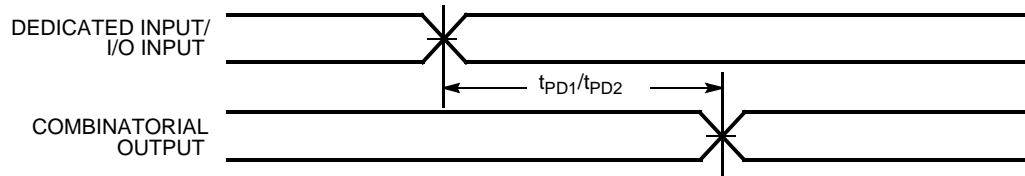


**Switching Waveforms (continued)**

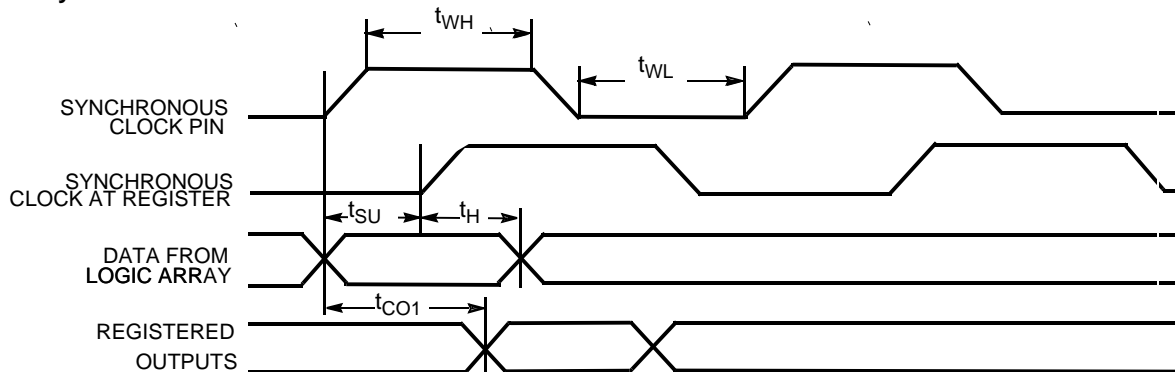
**Internal Combinatorial**



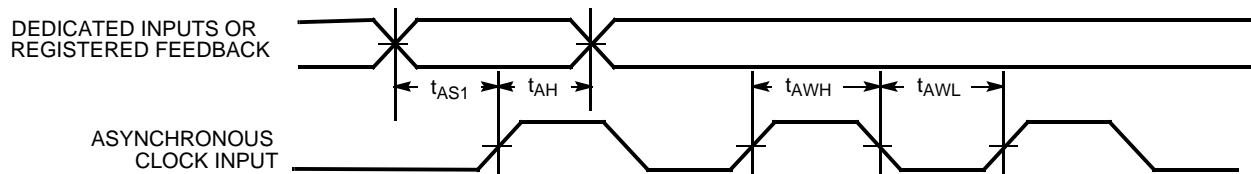
**External Combinatorial**



**External Synchronous**



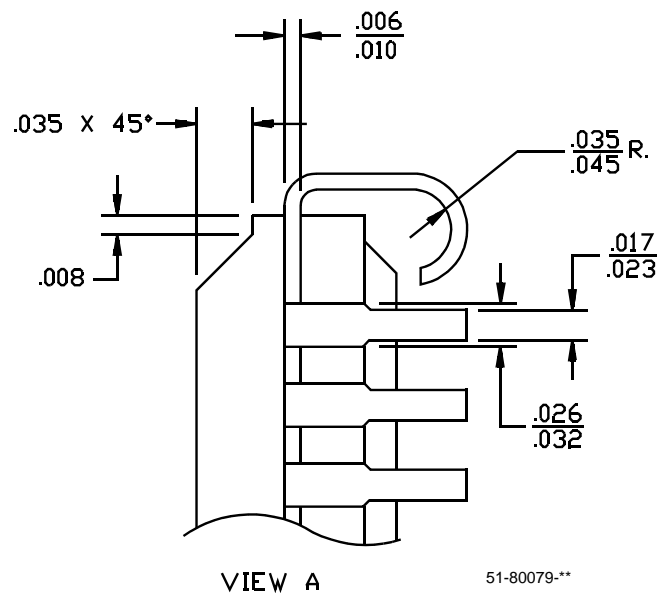
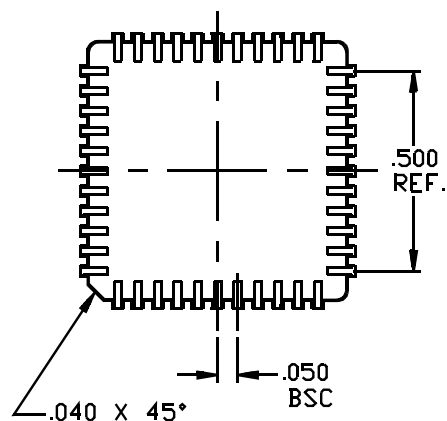
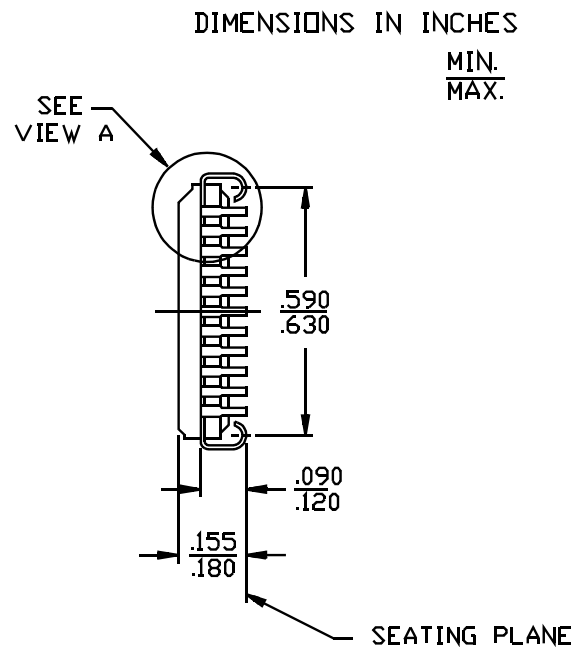
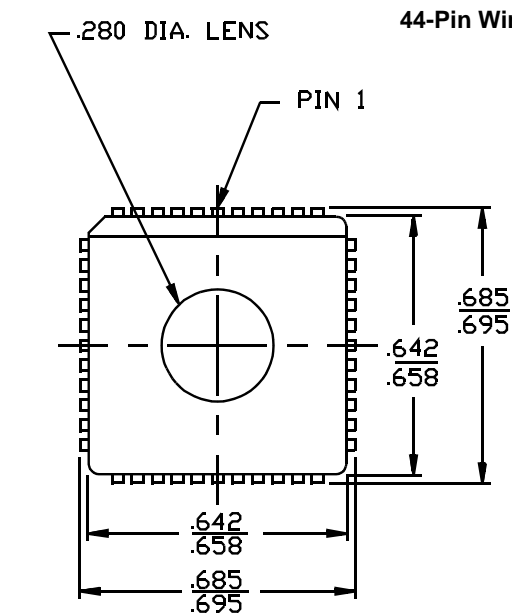
**External Asynchronous**



### Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
25	CY7C343B-25HC/HI	H67	44-Pin Windowed Leaded Chip Carrier	Commercial/Industrial
	CY7C343B-25JC/JI	J67	44-Lead Plastic Leaded Chip Carrier	
30	CY7C343B-30JC/JI	J67	44-Lead Plastic Leaded Chip Carrier	Commercial/Industrial
35	CY7C343B-35HC/HI	H67	44-Pin Windowed Leaded Chip Carrier	Commercial/Industrial
	CY7C343B-35JC/JI	J67	44-Lead Plastic Leaded Chip Carrier	

### Package Diagrams

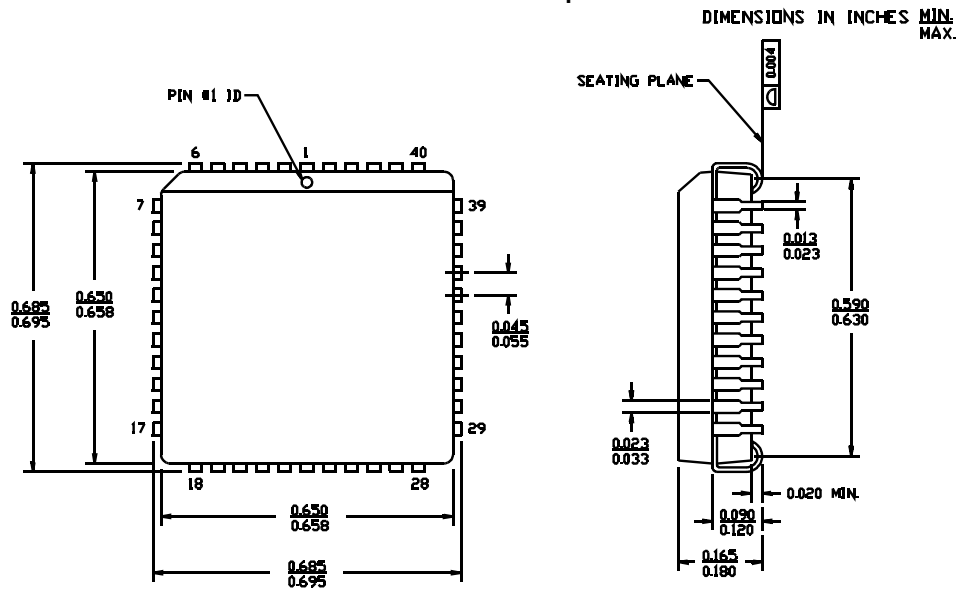


51-80079-\*\*



**Package Diagrams** (continued)

**44-Lead Plastic Leaded Chip Carrier J67**



51-85003-A

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**CY7C343B**

## Document History Page

Document Title: CY7C343B 64-Macrocell Max ® EPLD Document Number: 38-03038				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	106461	07/11/01	SZV	Change from Spec Number: 38-00862 to 38-03038
*A	122237	12/28/02	RBI	Power up requirements added to Operating Range Information
*B	213375	See ECN	FSG	Added note to title page: "Use Ultra37000 For All New Designs"